

QSFP-DD



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QSFP-DD MSA GROUP ANNOUNCES NEW HARDWARE SPECIFICATION

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Quad Small Form Factor Pluggable Double Density MSA releases 3.0 Hardware Specification

Göteborg, Sweden – September 19, 2017 – The Quad Small Form Factor Pluggable Double Density (QSFP-DD) Multi Source Agreement (MSA) group has released an updated 3.0 Hardware specification for the new QSFP-DD form factor. In total, 62 companies came together in support of the QSFP-DD MSA to address the industry need for a high-density, high-speed networking solution.

Established in March 2016, the QSFP-DD MSA group accepted the challenge to meet the market demand for a next generation high-density, high-speed pluggable backwards compatible module form factor. The MSA group has succeeded in releasing a 3.0 Hardware specification with broad market support that overcomes the technical challenges of specifying a QSFP28 compatible double-density interface. The QSFP-DD specification defines mechanical, electrical, and thermal management requirements to enable multi-vendor interoperability.

QSFP-DD pluggable modules can support quadruple the bandwidth of conventional QSFP modules, allowing networking equipment to keep pace with advances in ASIC technology. Systems designed for QSFP-DD modules will be backwards compatible with existing QSFP form factors and provide increased flexibility for end users, network platform designers and integrators.

The QSFP-DD 3.0 Hardware specification defines a module and both a stacked height integrated cage/connector system and a single height cage/connector system. The MSA has redefined the scope on the QSFP form factor, the industry's leading multi-lane pluggable form factor used across Ethernet, Fibre Channel and InfiniBand. QSFP was initially launched at 40 Gbps and 100 Gbps network applications and now QSFP-DD supports up to 400 Gbps in aggregate over an 8 x 50 Gbps electrical interface.

QSFP-DD MSA founder-promoters include Broadcom, Brocade, Cisco, Corning, Finisar, Foxconn Interconnect Technology, Huawei, Intel, Juniper Networks, Lumentum, Luxtera, Mellanox Technologies, Molex, Oclaro, and TE Connectivity.

Contributors include Acacia, ACON, Alibaba, Amphenol, Applied Optoelectronics, APRESIA Systems, Cavium, Celestica, Ciena, ColorChip, Dell EMC, Delta Products, Fujitsu Optical Components, Genesis, H3C, Hisense Broadband, Hitachi Metals, Hewlett Packard Enterprise, Innovium, Inphi, Ixia, JPC, Kaia, LEONI, Lorum, Luxshare-ICT, MACOM, MaxLinear, MultiLane, NeoPhotonics, Nokia, Panduit, PHY-SI, Ranovus, Samtec, SENKO, Semtech, Sico, Siemon, Skorpion Technologies, Source Photonics, Spectra7 Microsystems, Spirent, Sumitomo Electric, US Conec, Xilinx, and Yamaichi Electronics.

The QSFP-DD form factor specification is available for free download at the QSFP-DD MSA website www.qsfp-dd.com.

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ABOUT US

The QSFP-DD MSA will define a new pluggable form factor that supports 8 high speed electrical interfaces connecting to the host. This will include a mechanical module, a 2x1 Cage with connector, thermal, pinout and management specifications. The QSFP-DD will be able to support both optical and copper interfaces, but those physical layer specifications will be done outside of the MSA specification as is usual for form factor MSA specifications.

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"This MSA is open to any interested party who wants to join. All members will be provided a meaningful opportunity to participate in MSA's standards development on a non-discriminatory basis. In addition, MSA guarantees that the processes for participating in its standards development efforts will be transparent to all members."

If you are interested in being a member, please contact us at: info@qsfp-dd.com